

## R E M A R K S

The rejection of claims 1-8 under 35 USC 102(e) as being anticipated by Tamura et al (USP 7,195,857) is respectfully traversed.

Claims 1 to 8 of the subject application are directed to an organic mold for transferring micropatterns to a substrate, the organic mold having a reverse pattern face of the face of the micropatterns being transferred and with the mold being fabricated from a specified resin composition which requires the addition of 0.01 to 200 parts by weight of a silicon or fluorine compound as set forth in paragraph (d). As can be seen from the subject specification, the subject invention was devised to solve the problems of conventional methods for forming micropatterns even by photolithography (see page 1, line 13 to page 2, line 11), and provides for a novel organic mold for transferring micropatterns that can be easily and repeatedly lifted off from a substrate without irreversible adhesion or generation of defects (see page 2, lines 15 to 19).

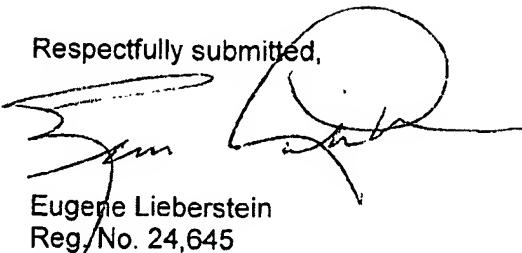
Meanwhile, Tamura '857 discloses a protective film made of a resist curable resin composition, which is used to produce a printed circuit board (PCB). Tamura '857 teaches that the resist curable resin composition is particularly suited for use as an insulating protective coating film for a PCB because it is superior in photosensitivity and developability and also provides superior adhesion to the substrate, etc., when cured to form a thin film. According to Tamura '857, the insulating protective coating film is formed by applying a resist curable resin composition on a substrate, drying while heat-treating, exposing to light through a negative mask with a desired exposure pattern, developing while removing the non-exposure portion with a developing solution, and thermo curing the resist curable resin composition (see col. 27, lines 12 to 37 of Tamura '857), which is a typical photolithography.

A significant difference exists between the subject invention and Tamura in that in the subject invention as now defined in claim 1, as amended, the organic mold must have a pattern face which is the reverse of the pattern face of the micropatterns for transferring the micropatterns to a substrate. To do so, the micropatterns should be easily and repeatedly lifted off from the substrate. In this regard, please note that the organic mold of the subject invention, as indicated in paragraph (c), includes a silicone or fluorine containing compound. This compound acts as a functionalized additive imparting a good releasing property. In sharp contrast, the insulating film in Tamara '957 is prepared by photolithography and is superior in adhesion to a substrate. Moreover, none of the working examples in Tamura '857 employ or suggest adding any silicone or fluorine containing compound. Accordingly, Tamura '857 fails to disclose or teach an organic mold as defined in claim 1 for transferring micropatterns to a substrate much less having a reverse pattern face of the micropatterns being transferred. The film in Tamura '857 is not an organic mold and is instead a protective film for the printed circuit board (PCB) having a composition which provides superior adhesion to a substrate. The mold in Claim 1, by contrast, must be easily and repeatedly lifted off the substrate.

For all of the above reasons, claims 1-8 are clearly patentable over Tamura et al and the rejection under 35 USC 102(e) should now be withdrawn.

Reconsideration and allowance of claims 1-8 is respectfully solicited.

Respectfully submitted,

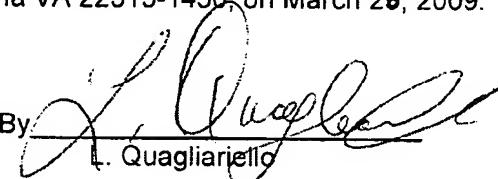
  
Eugene Lieberstein  
Reg. No. 24,645

Customer # 79681  
BAKER & HOSTETLER LLP  
45 Rockefeller Plaza  
New York, NY 10111  
Tel: 212-589-4634  
Fax: 212-589-4201

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I hereby certify that this correspondence is being sent to the USPTO via EFS Web to the Commissioner for Patents, P.O. Box 1450, Alexandria VA 22313-1450 on March 26, 2009.

By:

  
L. Quagliariello